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(54) ORGANIC ELECTROLUMINESCENT ELEMENT AND METHOD FOR MANUFACTURING THE SAME

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(58)	Field of Search	

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(57) ABSTRACT

An organic electroluminescent element which is highly precise and minute, uniform in light emission, free from cross talk, resistant to external pressure, and further excellent in sealing properties and a process for producing the above element. The organic electroluminescent element 1 which is equipped, between a lower electrode 3 and a counter eletrode 4 each on a substrate 2, with an intervening organic layer 5 comprising a light-emitting layer, comprises an inter-insulator film 6 having a coefficient of water absorption of at most 0.1% in a non-light-emitting element portion; step portions 9 in the inter-insulator layer 6 which define the boundary between a light-emitting element portion and a non-light-emitting element portion and which comprise rising parts almost perpendicular to the surface of the lower electrode 3; and a sealing plate or a sealing lid 7 which is placed over the inter-insulator layer 6 and which is attached to the substrate 2 via an adhesive layer 8.

31 Claims, 6 Drawing Sheets

